



In the United States Patent and Trademark Office

In re the Application of
Smith et al.

TI-25250

Serial No. 09/199,829

Art Unit: 2823

Filed: 11/25/98

Examiner: Eaton, K.

Title: Hydrogen plasma photoresist strip and polymeric residue
cleanup process for oxygen sensitive materials

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Amendment Under 37 CFR 1.111

September 28, 2000

Assistant Commissioner of
Patents and Trademarks
Washington, D. C. 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is
being deposited with the U.S. Postal Service as
First Class Mail in an envelope addressed to:
Commissioner of Patents and Trademarks,
Washington, D.C. 20231 on September 28, 2000.

Cecelia Grant

Responsive to the Examiner's Action of 04/28/00, please amend
this application as follows:

In the Specification:

Please delete the SUMMARY OF THE INVENTION section in the
disclosure on pages 4 through 6 and replace it with the following:

71 SUMMARY OF THE INVENTION

The objective of the instant invention is a method for removing
photoresist and residue from the surface of a wafer. The